

## SPU13N05L-VB Datasheet

## N-Channel 60 V (D-S) MOSFET

PRODUCT	T SUMMARY		
V <sub>DS</sub> (V)	$R_{DS(on)}(\Omega)$	I <sub>D</sub> (A)	Q <sub>g</sub> (Typ.)
60	$0.032 \text{ at V}_{GS} = 10 \text{ V}$	35 <sup>d</sup>	21.7
30	0.037 at V <sub>GS</sub> = 4.5 V	30 <sup>d</sup>	21.7

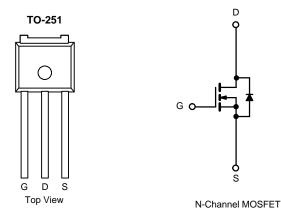
#### **FEATURES**

- Halogen-free According to IEC 61249-2-21 Definition
- Trench Power MOSFET
- 100 % R<sub>g</sub> and UIS Tested
- Compliant to RoHS Directive 2002/95/EC





- Power Supply
  - Secondary Synchronous Rectification
- DC/DC Converter



<b>ABSOLUTE MAXIMUM RATINGS</b>	$T_C = 25  ^{\circ}C$ , unless other	erwise noted			
Parameter		Symbol	Limit	Unit	
Drain-Source Voltage	V <sub>DS</sub>	60	V		
Gate-Source Voltage	$V_{GS}$	± 20			
Continuous Drain Current (T <sub>.I</sub> = 150 °C)	T <sub>C</sub> = 25 °C	I-	35 <sup>d</sup>	А	
Continuous Diairi Current (1) = 130 °C)	T <sub>C</sub> = 70 °C	- I <sub>D</sub>	30 <sup>d</sup>		
Pulsed Drain Current	I <sub>DM</sub>	100	Α		
Avalanche Current	I <sub>AS</sub>	40			
Single Avalanche Energy <sup>a</sup>	L = 0.1 mH	E <sub>AS</sub>	80	mJ	
W	T <sub>C</sub> = 25 °C	В	59.5 <sup>b</sup>	W	
Maximum Power Dissipation <sup>a</sup>	T <sub>A</sub> = 25 °C <sup>c</sup>	P <sub>D</sub>	2.7		
Operating Junction and Storage Temperature Ra	T <sub>J</sub> , T <sub>stg</sub>	- 55 to 150	°C		

THERMAL RESISTANCE RATINGS				
Parameter	Symbol	Limit	Unit	
Junction-to-Ambient (PCB Mount) <sup>c</sup>	R <sub>thJA</sub>	46	°C/W	
Junction-to-Case (Drain)	R <sub>thJC</sub>	2.1	- C/VV	

#### Notes:

- a. Duty cycle  $\leq$  1 %.
- b. See SOA curve for voltage derating.c. When mounted on 1" square PCB (FR-4 material).
- d. Package limited.

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<b>SPECIFICATIONS</b> $T_J = 25^{\circ}$	Symbol	Test Conditions	Min.	Тур.	Max.	Unit
Static	Зуппол	rest conditions	IVIIII.	тур.	IVIAA.	Offic
	.,	V 0.V 1 050 A				
Drain-Source Breakdown Voltage	V <sub>DS</sub>	$V_{DS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	60			V
Gate Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_{D} = 250 \mu\text{A}$	2.0		3.5	
Gate-Body Leakage	I <sub>GSS</sub>	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 250	nA
	I <sub>DSS</sub>	$V_{DS} = 60 \text{ V}, V_{GS} = 0 \text{ V}$			1	
Zero Gate Voltage Drain Current		$V_{DS} = 60 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 125 \text{ °C}$			50	μΑ
		$V_{DS} = 60 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 150 ^{\circ}\text{C}$			250	
On-State Drain Current <sup>a</sup>	$I_{D(on)}$	$V_{DS} \ge 10 \text{ V}, V_{GS} = 10 \text{ V}$	50			Α
Drain-Source On-State Resistance <sup>a</sup>	e <sup>a</sup> R <sub>DS(on)</sub> -	$V_{GS} = 10 \text{ V}, I_{D} = 12 \text{ A}$		0.032		Ω
Diam-Source On-State Resistance		$V_{GS} = 4.5 \text{ V}, I_D = 10 \text{ A}$		0.037		
Forward Transconductance <sup>a</sup>	9 <sub>fs</sub>	V <sub>DS</sub> = 15 V, I <sub>D</sub> = 10 A		110		S
Dynamic <sup>b</sup>						
Input Capacitance	C <sub>iss</sub>			1100		pF
Output Capacitance	C <sub>oss</sub>	$V_{GS} = 0 \text{ V}, V_{DS} = 30 \text{ V}, f = 1 \text{ MHz}$		281		
Reverse Transfer Capacitance	C <sub>rss</sub>			130		
Tatal Cata Chausa C	Qg	V <sub>DS</sub> = 30 V, V <sub>GS</sub> = 10 V, I <sub>D</sub> = 10 A		46		nC
Total Gate Charge <sup>c</sup>				28		
Gate-Source Charge <sup>c</sup>	Q <sub>gs</sub>	$V_{DS} = 30 \text{ V}, V_{GS} = 4.5 \text{ V}, I_{D} = 10 \text{ A}$		7		
Gate-Drain Charge <sup>c</sup>	Q <sub>gd</sub>			6.7		
Gate Resistance	R <sub>g</sub>	f = 1 MHz	0.4	2	4	Ω
Turn-On Delay Time <sup>c</sup>	t <sub>d(on)</sub>			8	16	ns
Rise Time <sup>c</sup>	t <sub>r</sub>	$V_{DD} = 30 \text{ V, R}_{1} = 1.5 \Omega$		9	18	
Turn-Off Delay Time <sup>c</sup>	t <sub>d(off)</sub>	$I_D \cong 10 \text{ A}, V_{GEN} = 10 \text{ V}, R_q = 1 \Omega$		35	53	
Fall Time <sup>c</sup>	t <sub>f</sub>	Ç		9	18	
Drain-Source Body Diode Ratings ar		stics T <sub>C</sub> = 25 °C <sup>b</sup>			-	
Continuous Current	I <sub>S</sub>				50	
Pulsed Current	I <sub>SM</sub>				100	Α
Forward Voltage <sup>a</sup>	V <sub>SD</sub>	I <sub>F</sub> = 10 A, V <sub>GS</sub> = 0 V		0.75	1.5	V
Reverse Recovery Time	t <sub>rr</sub>	·F .57.9.65 5 .		34	51	ns
Peak Reverse Recovery Current		$I_{\rm F} = 10 \text{ A},  dI/dt = 100  A/\mu s$		2	3	A
Reverse Recovery Charge	I <sub>RM(REC)</sub>	1 <sub>F</sub> = 10 Λ, αι/αι = 100 Λ/μδ		34	51	nC

#### Notes:

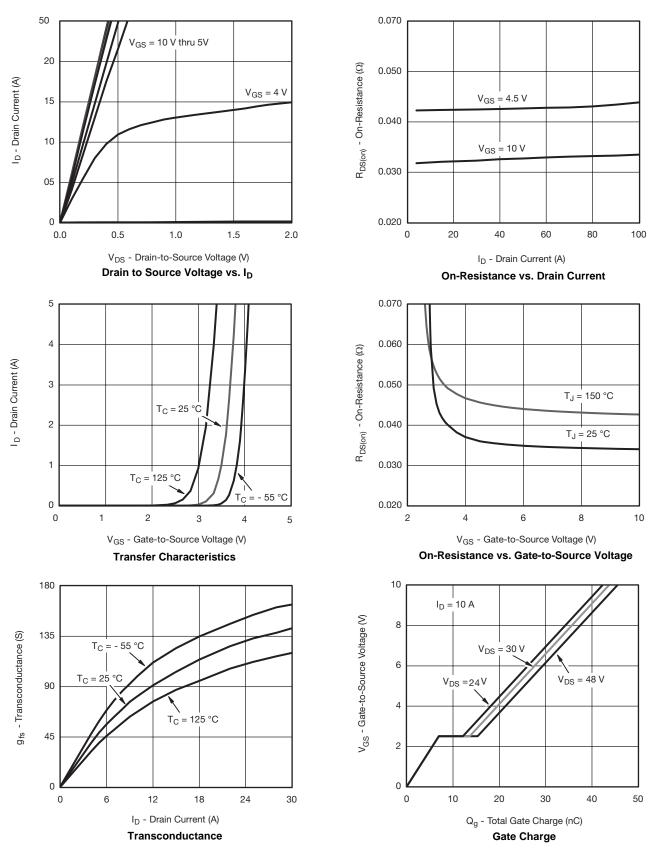
- a. Pulse test; pulse width  $\leq 300~\mu s,$  duty cycle  $\leq 2~\%.$
- b. Guaranteed by design, not subject to production testing.
- c. Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

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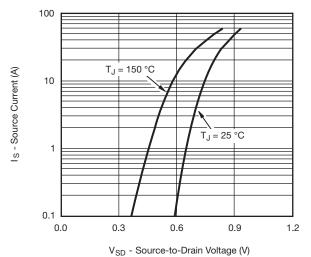


## TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

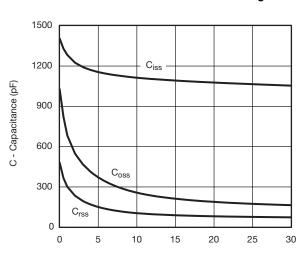




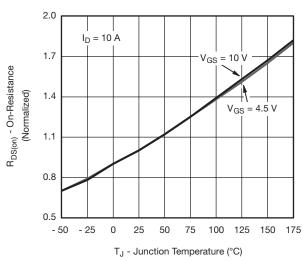
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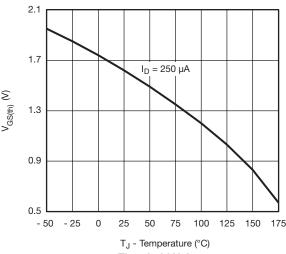
Source-Drain Diode Forward Voltage

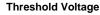


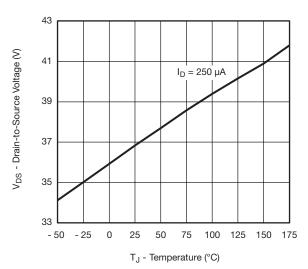
 $V_{DS}$  - Drain-to-Source Voltage (V)  $\label{eq:capacitance}$ 



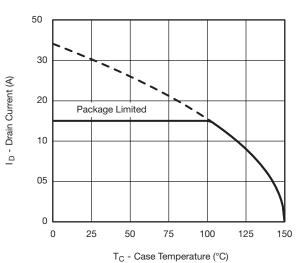
On-Resistance vs. Junction Temperature







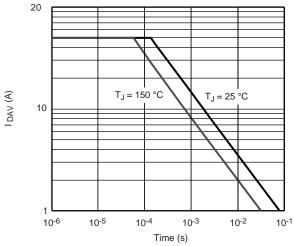
Drain Source Breakdown vs. Junction Temperature

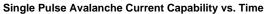


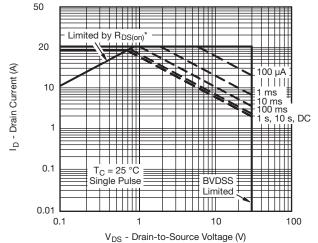
**Current Derating** 



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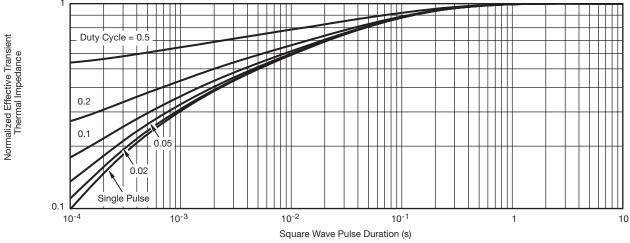






 $^{\star}$  V  $_{GS}$  > minimum V  $_{GS}$  at which R  $_{DS(on)}$  is specified

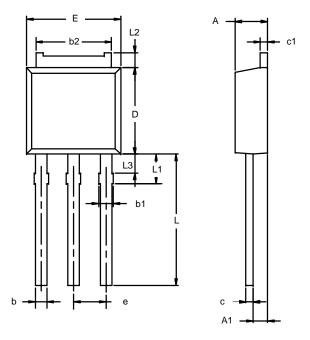




Normalized Thermal Transient Impedance, Junction-to-Case



## TO-251AA (DPAK)



Note: Dimension L3 is for reference only.

in 21 39 71 76 23 46	Max 2.38 1.14 0.89 1.14 5.43 0.58	0.087 0.035 0.028 0.030 0.206	0.094 0.045 0.035 0.045 0.214	
39 71 76	1.14 0.89 1.14 5.43	0.035 0.028 0.030 0.206	0.045 0.035 0.045	
71 76 23	0.89 1.14 5.43	0.028 0.030 0.206	0.035 0.045	
76 23	1.14 5.43	0.030	0.045	
23	5.43	0.206		
			0.214	
16	0.58	0.040		
		0.018	0.023	
16	0.58	0.018	0.023	
97	6.22	0.235	0.245	
48	6.73	0.255	0.265	
2.28 BSC		0.090 BSC		
39	9.53	0.350	0.375	
91	2.28	0.075	0.090	
39	1.27	0.035	0.050	
15	1.52	0.045	0.060	
	39 15	15 1.52		

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